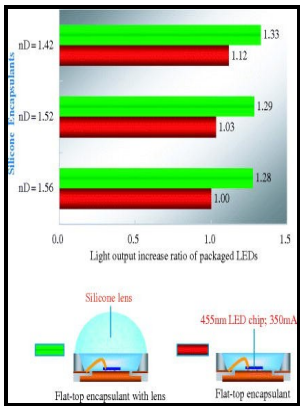
Influence of contamination on the long-term reliability of chip-on-board (COB) technology.

Oxford Brookes University - Thermo



Description: -
-Influence of contamination on the long-term reliability of chip-on-board (COB) technology.
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Characteristic enhancement of white LED lamp using low temperature co

These challenges are addressed by extensive bonding accuracy tests, a design of experiments approach for optimizing wire bond process parameters, reliability testing, and detailed materials characterization of the metallurgical integrity of the wire bonds.

A chip

Smaller, but significant, savings in component height can also be achieved since the base of the chip is directly bonded to the board or substrate.

Evaluation of wire bonding performance, process conditions, and metallurgical integrity of chip on board wire bonds

However, if the boards are to be used for military, automotive or avionics applications, there is a legitimate concern about the reliability issue. Parts Materials and Packaging, Vol 3 4 , December 1967. Palomar has COB customers in all industries, particularly aerospace.

Influence on temperature distribution of COB deep UV LED due to different packaging density and substrate type

As die-attach material different solder materials and Ag-filled thermal adhesives have been used. The aim was to dispense the material in the form of a circle 10mm diameter, or 10mm square in the case of the stencil printing application.

Cleanroom Requirement Debated for Chip

All had high lap shear strengths and good dispensing properties and the screen printable materials were good in thermal cycling when on FR4. Thermo-mechanical reliability during technology development of power chip-on-board assemblies with encapsulation.

Influence on temperature distribution of COB deep UV LED due to different packaging density and substrate type

Abstract Glob-top resins are providing a low cost packaging solution for chip on board technology. DCA turns the chip upside down and attaches it directly to the board, requiring an underfill material between the die and the board. After wirebonding, the components were glob topped and cured.

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